

Maximum Ratings and Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	RABF22	RABF24	RABF26	RABF28	RABF210	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	400	600	800	1000	V
RMS Reverse Voltage	V _{R(RMS)}	140	280	420	560	700	V
Average Rectified Output Current (Note 5) @ T _C = +100°C	I _O	2.0					A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	60					A
I ² t Rating for Fusing (1ms < t < 8.3ms)	I ² t	14.94					A ² S
Maximum Forward Voltage (Per Element) @ I _F = 2.0A	V _{FM}	1.3					V
Maximum Reverse Recovery Time (Note 6)	t _{RR}	150		250		500	ns
Peak Reverse Current @ T _A = +25°C At Rated DC Blocking Voltage (Note 7) @ T _A = +125°C	I _R	5.0 200					μA
Typical Total Capacitance (Per Element) (Note 8)	C _T	17					ns

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 5) (Per Element)	R _{θJA}	63	°C/W
Typical Thermal Resistance, Junction to Lead (Per Element)	R _{θJL}	25	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

- Notes:
- Device mounted on aluminum substrate PC board with 1.3mm² solder pad.
 - Reverse Recovery Test Conditions: I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A.
 - Short duration pulse test used to minimize self-heating effect.
 - Measured at 1.0MHz and applied reverse voltage of 4.0V D.C.

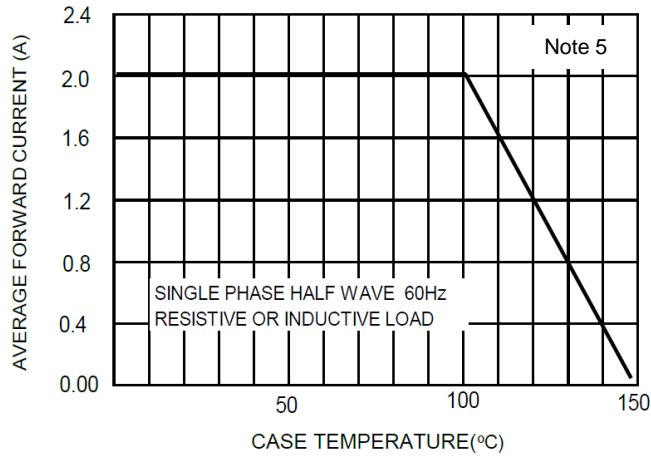


Figure1. Forward Current Derating

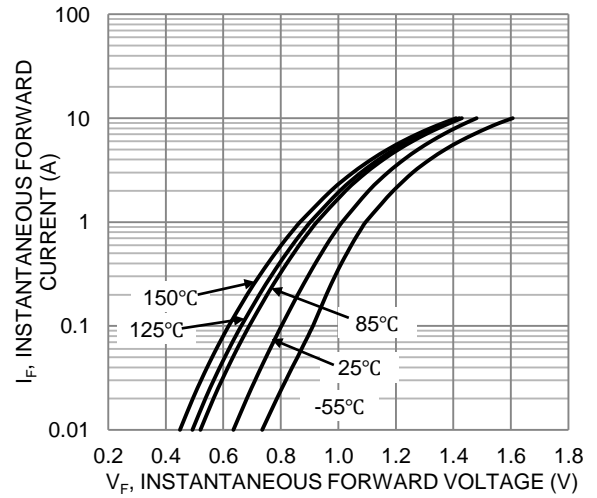


Figure 2. Typical Forward Characteristics

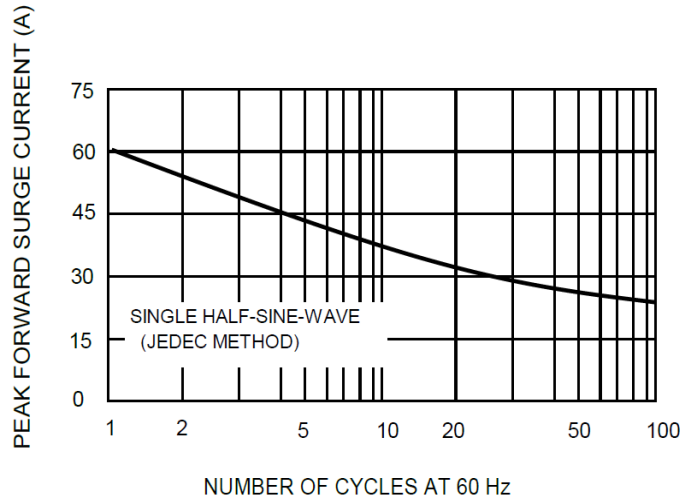


Figure 3. Maximum Non-Repetitive Forward Surge Current

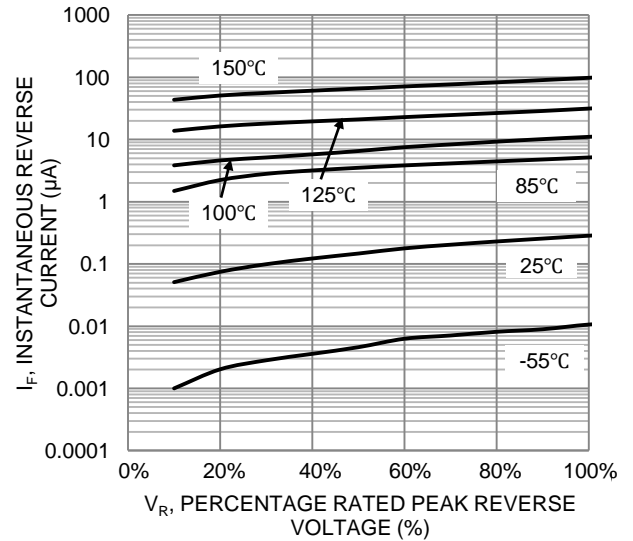


Figure 4. Typical Reverse Characteristics

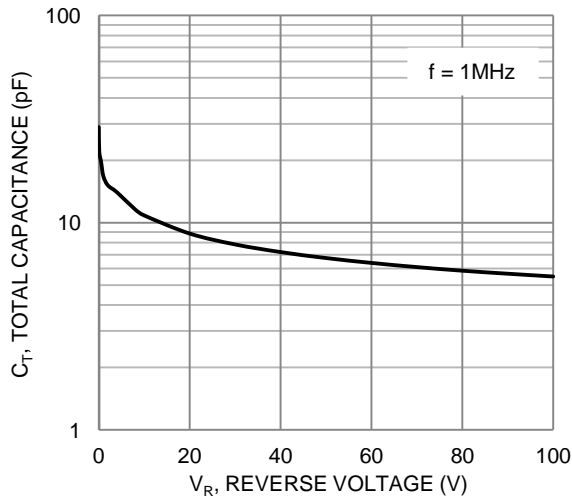
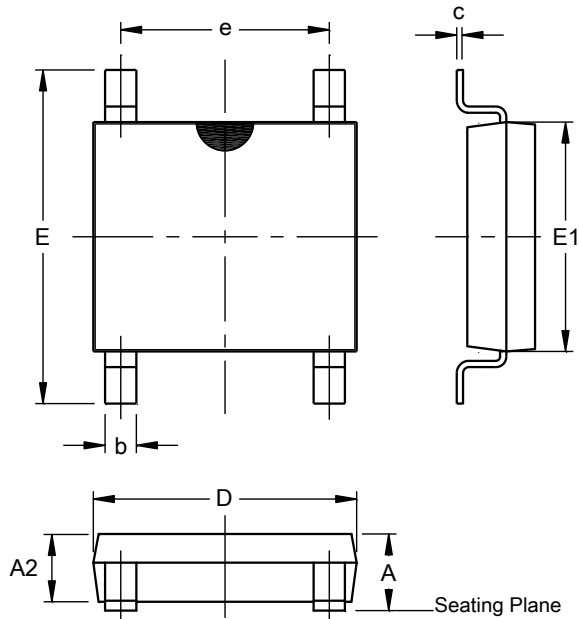


Figure 5. Typical Total Capacitance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOPA-4 (Type B)

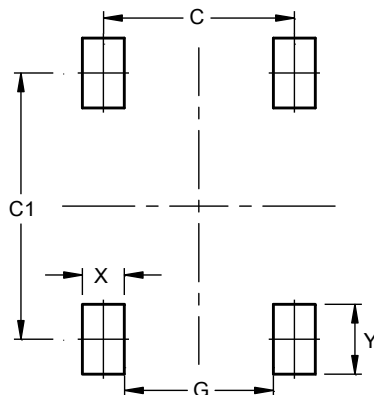


SOPA-4 (Type B)			
Dim	Min	Max	Typ
A	1.15	1.30	--
A2	1.00	1.25	--
b	0.50	0.70	--
c	0.15	0.25	--
D	4.80	5.30	--
E	6.00	6.80	--
E1	4.20	4.60	--
e	3.80	4.20	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOPA-4 (Type B)



Dimensions	Value (in mm)
C	4.10
C1	5.72
G	3.20
X	0.90
Y	1.50

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